

CURRENT STATUS OF NANOIMPRINT LITHOGRAPHY DEVELOPMENT IN CNMM

February 17th 2005

Eung-Sug Lee, Jun-Ho Jeong

Korea Institute of Machinery & Materials

Outlines

I. PROCESS TECHNOLOGY

- Single Step UV-NIL
 - UV-NIL using an Elementwise Patterned Stamp (EPS) in a Low Vacuum or Atmospheric Environment
 - UV-NIL for Uniform and Minimum Residual Layer
- Step and Repeat UV-NIL
 - High Throughput Step-and-Repeat UV-NIL using a Large Area Stamp

II. APPLICATION TECHNOLOGY

- Nano Wire Grid Polarizer
- Photonic Band Gap Device

III. TOOL TECHNOLOGY

- Single-Step UV-NIL Tool

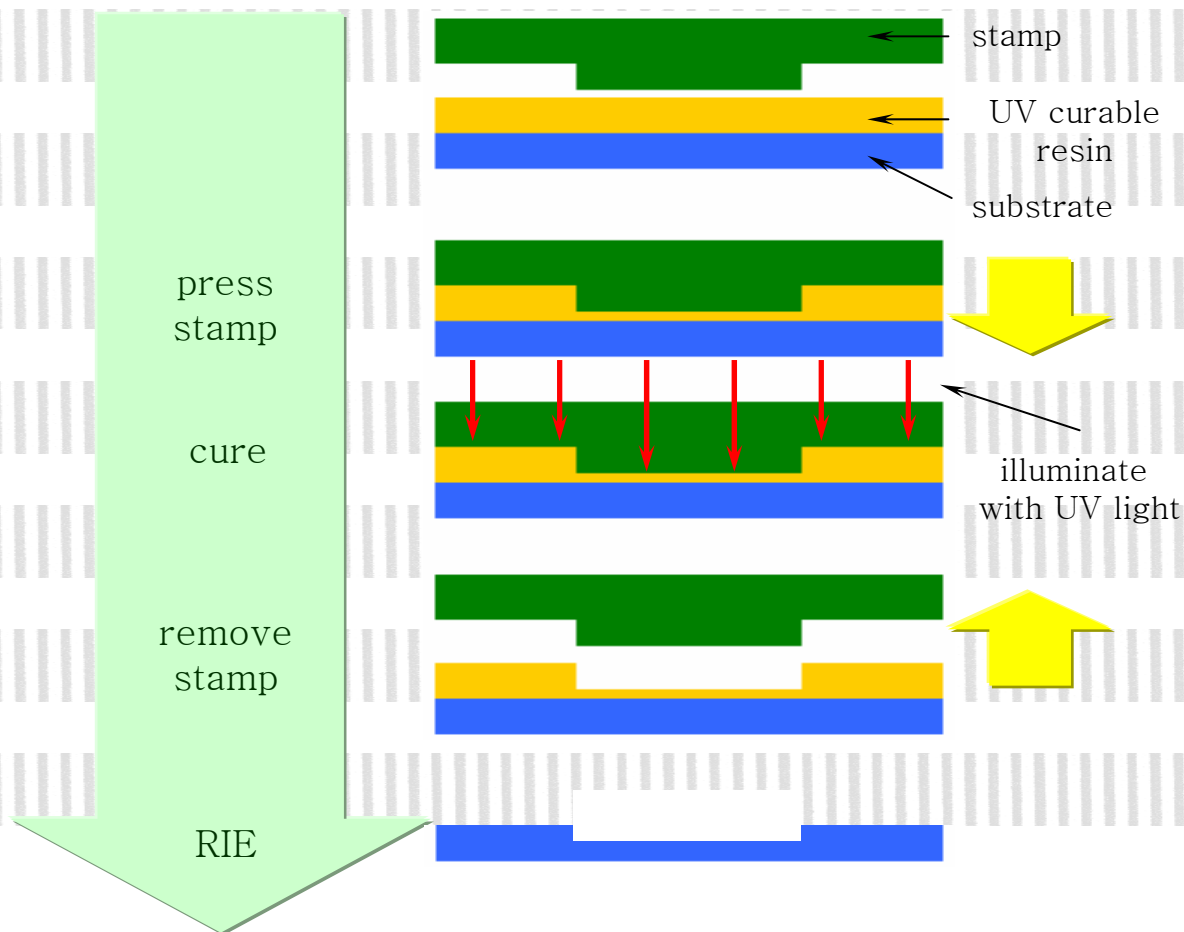
IV. SUMMARY

Process
technology

Single step UV-NIL

UV-NIL using a elementwise patterned
stamp (EPS) in a low vacuum
environment

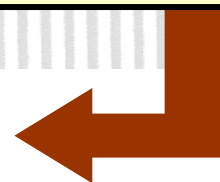
Schematic of UV nanoimprint lithography (UV-NIL)



Characteristics of UV-nanoimprint lithography

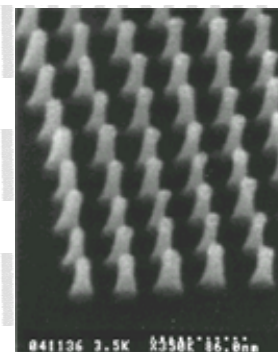
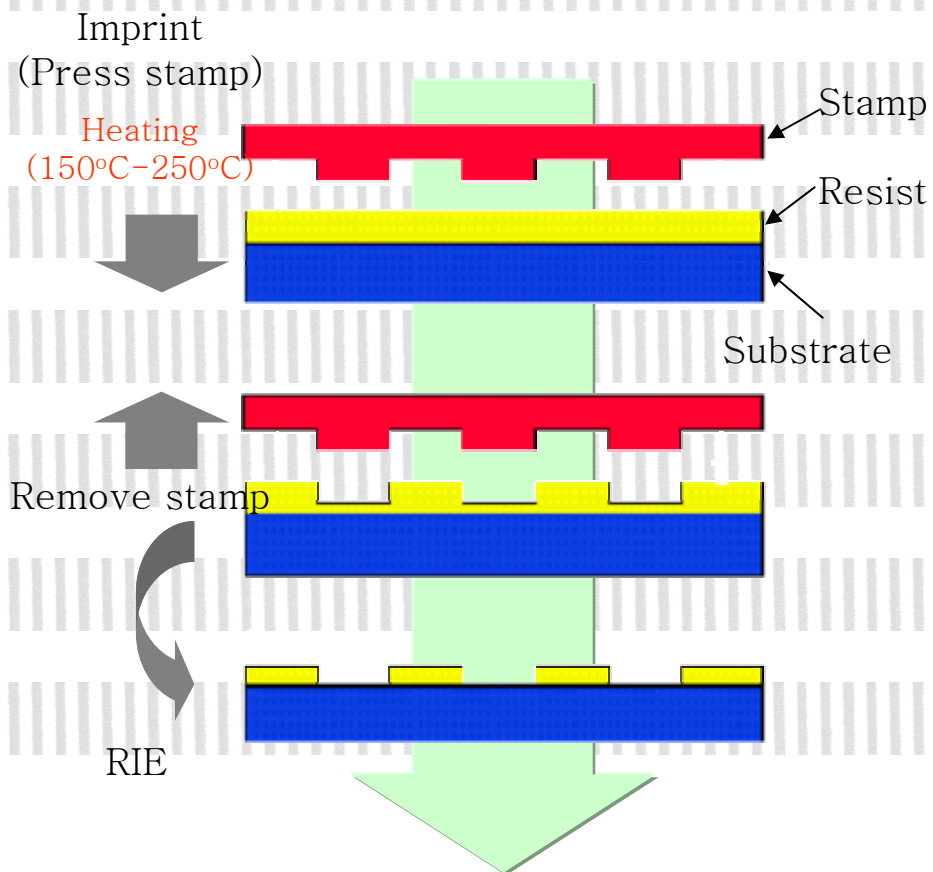
	Thermal type NIL	UV type NIL
Resin	Thermoplastic polymer	UV curable resin
Stamp material	Silicon, Nickel	Quartz, glass (transparent)
Processing temperature	$> T_g$ (glass transition temperature)	Room temperature
Processing pressure	High (~ 30 bar)	Low (~ 1 bar)

- Advantages for mass production, multi-layer process, and step & repeat process

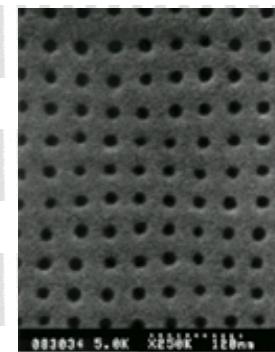


Recent studies on NIL

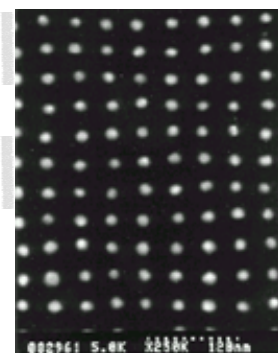
5 Nanoimprint lithography- Prof. Chou, Princeton University, 1995



Imprint mold with
10nm
diameter pillars



10nm diameter holes
imprinted in PMMA



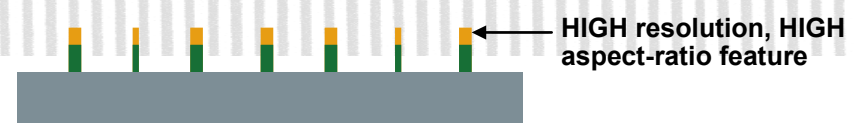
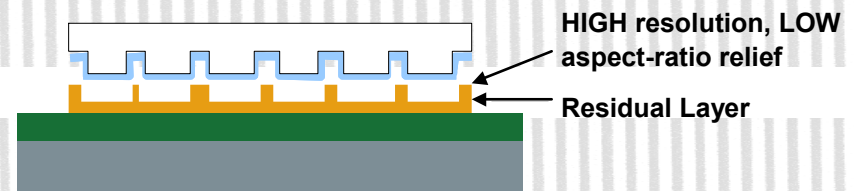
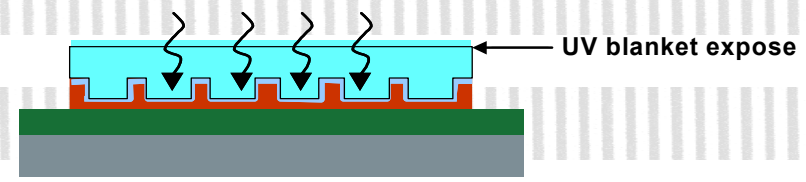
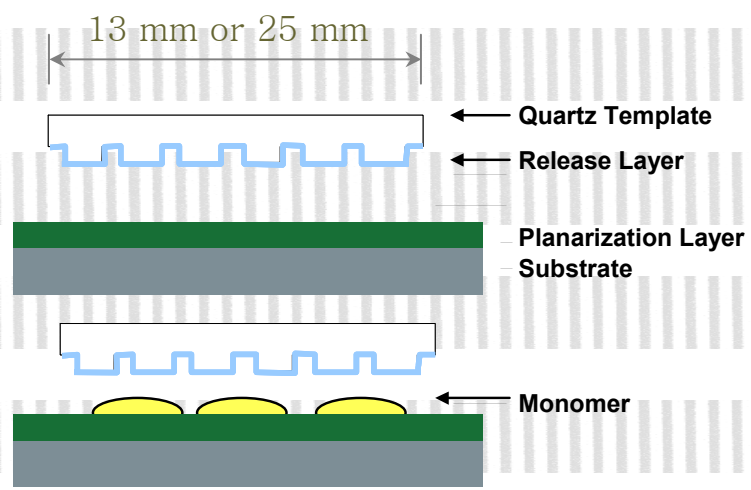
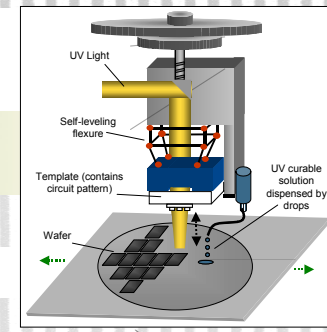
10nm diameter metal
dots fabricated by NIL

Recent studies on NIL

5 UV-Imprint lithography

- University of Texas at Austin (Sreenivasan et al.), 1999
- Molecular Imprints Inc.

■ Step & Flash Imprint Lithography (SFIL)



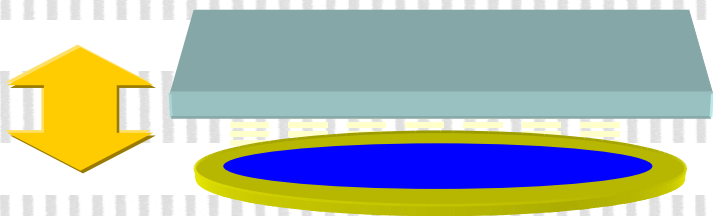
Motivations

- Step & repeat type UV-NIL using a small area (≤ 1 in.) stamp
 - ⇒ Low-throughput
 - (The imprint time is 2-3 minutes for each field and 10-20 minutes for a 4 in. wafer)
- Single step UV-NIL using a large-area stamp in a medium/ high-vacuum environment
 - ⇒ requires a vacuum-compatible system and UV curable resin
- For high-throughput manufacturing
 - ⇒ We have developed new UV-NIL processes using a large-area stamp in a low-vacuum or atmospheric environment

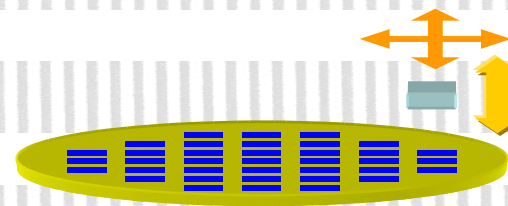
Elementwise patterned stamp

In a low vacuum-pressure or atmospheric environment

Single-step UV-NIL using a large area flat stamp



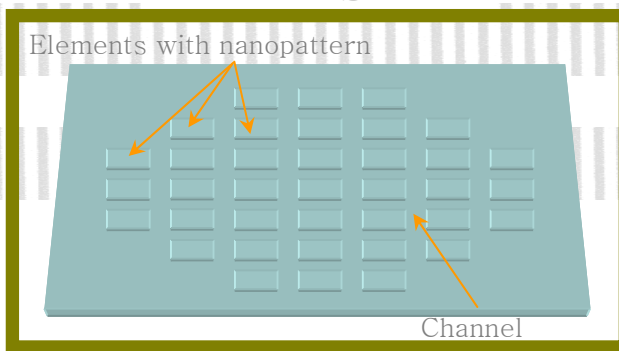
Step-and-repeat UV-NIL using a small stamp



Advantages

- High-throughput

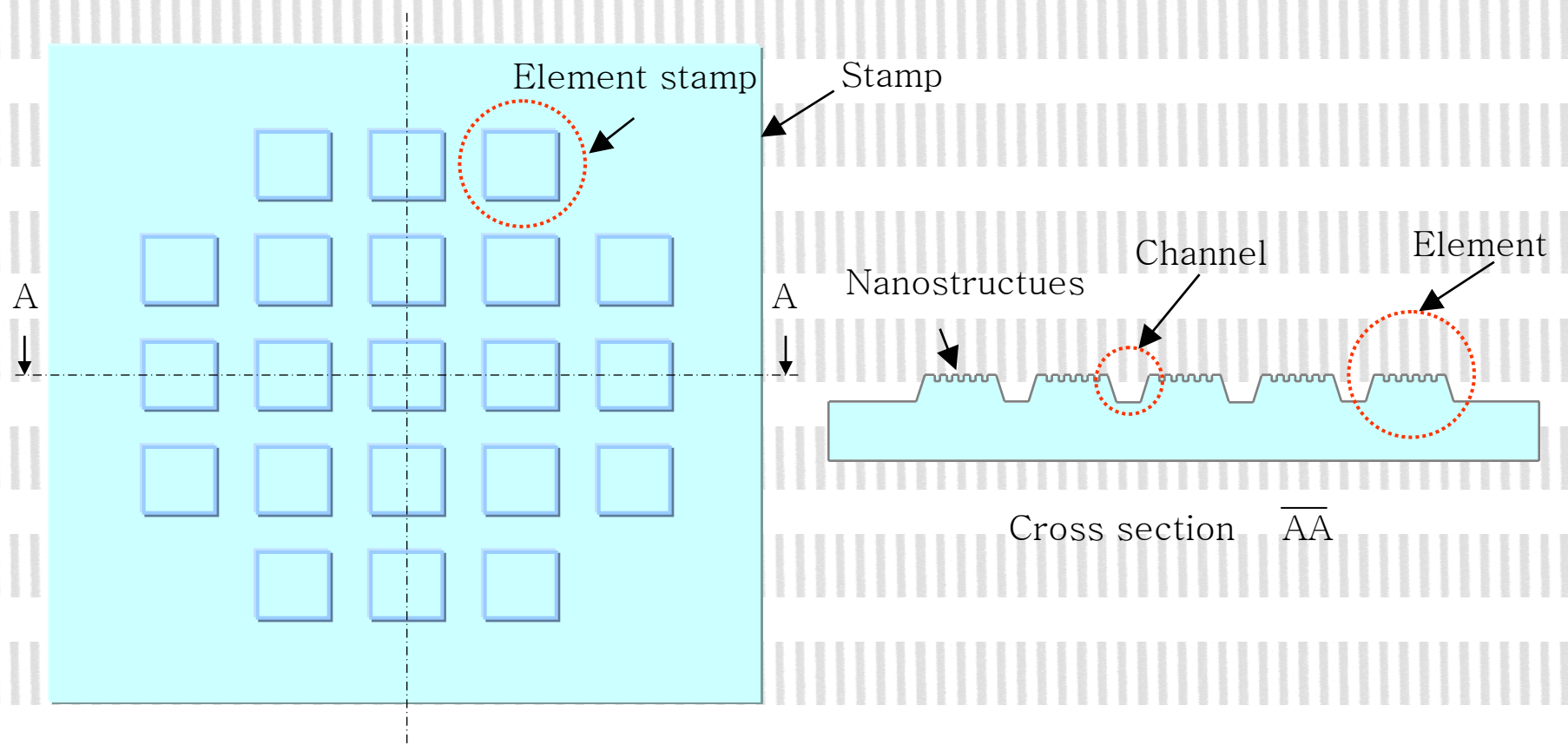
UV-NIL using EPS



Advantages

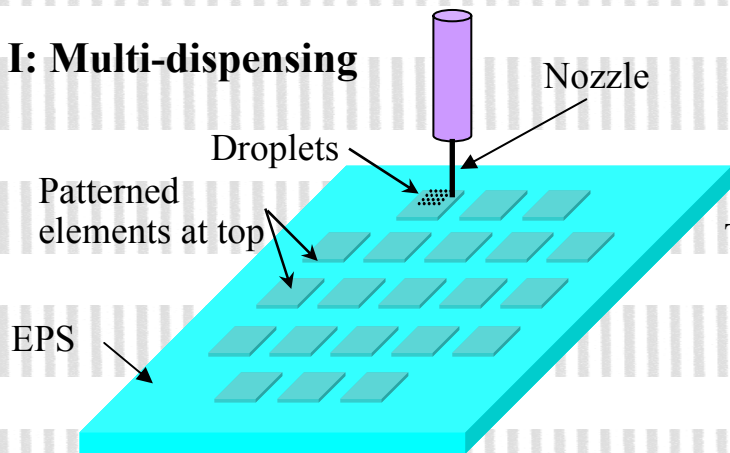
- Low-cost stamp
- Prevention of air entrapment
- Easy release
- Precise alignment for each field

Elementwise patterned stamp

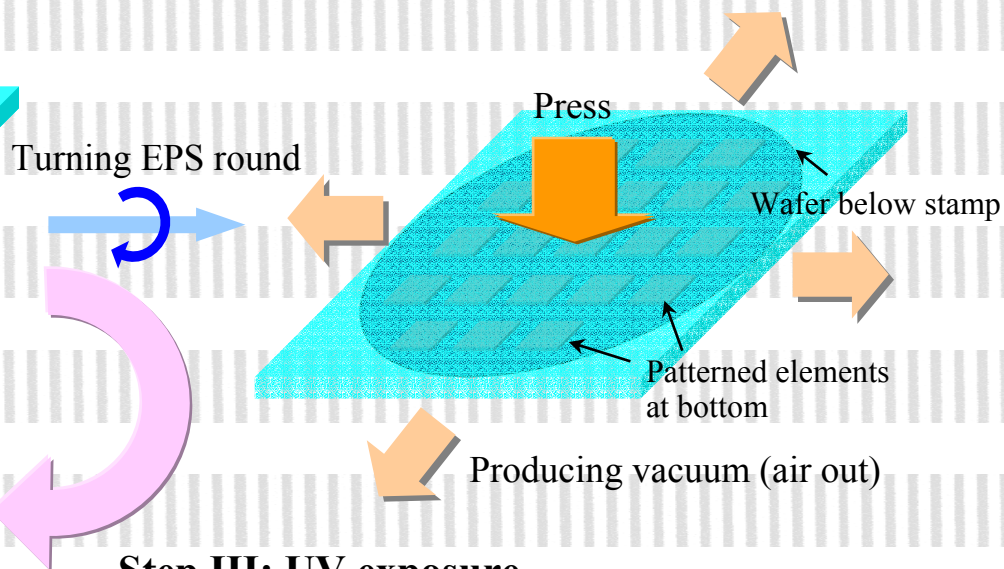


UV-NIL process using EPS

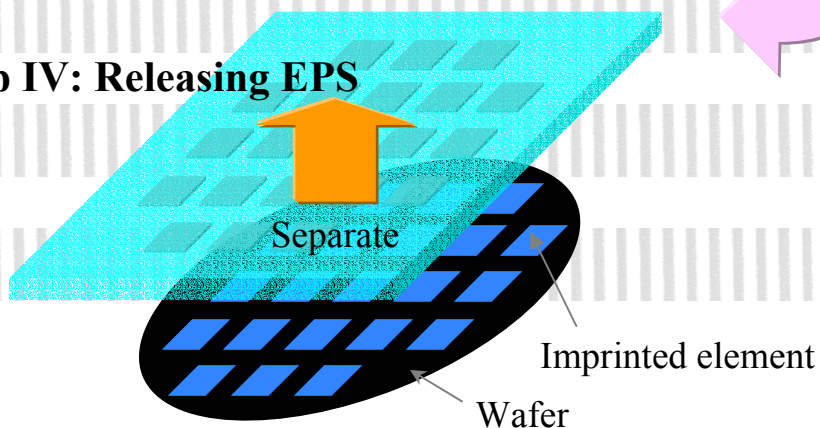
Step I: Multi-dispensing



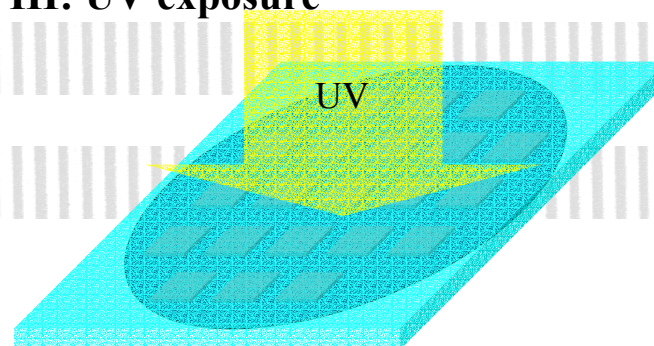
Step II: Pressing EPS



Step IV: Releasing EPS



Step III: UV exposure

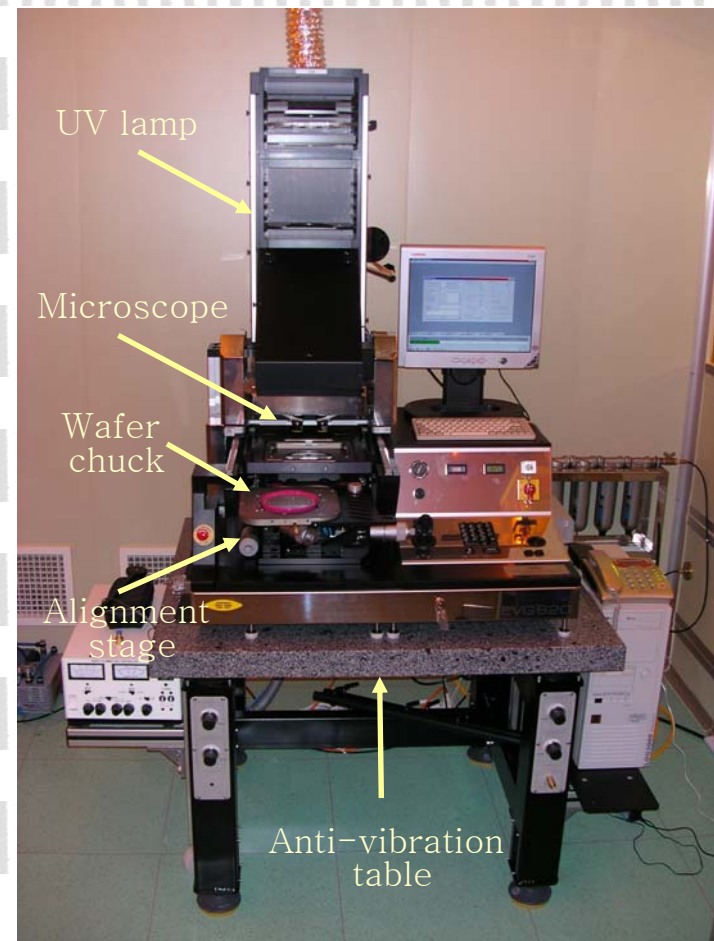


UV-NIL process using EPS

- Equipment- EVG620-NIL
 - Use 4 in. wafer
 - Vacuum hard contact mode

Parameters	
Pressure	800mbar
Exposure time	60 sec
Exposure intensity	36 mW/cm ²

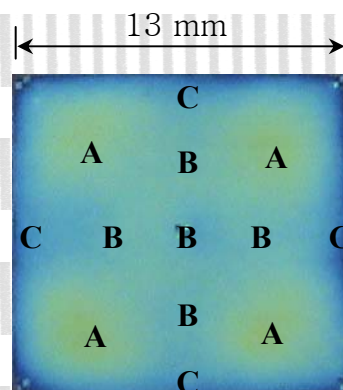
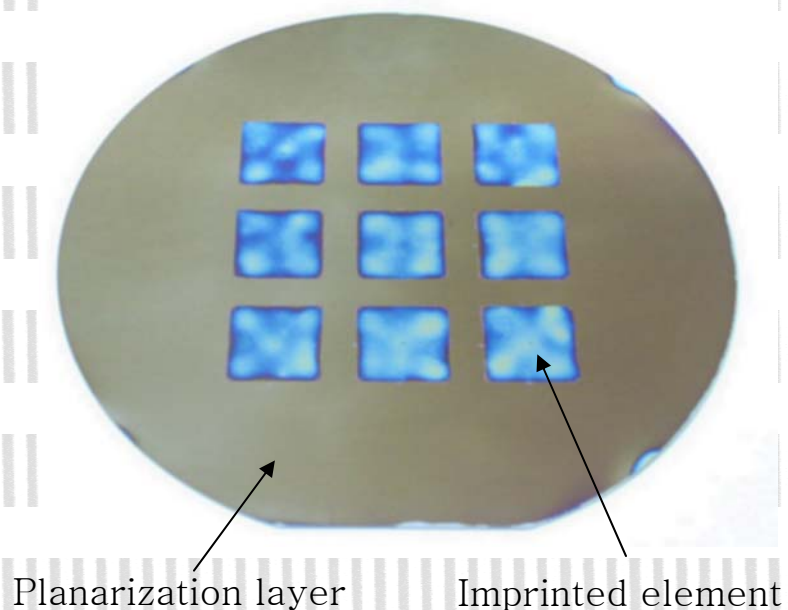
- UV curable resist
 - PAK01(viscosity = 7 cps)



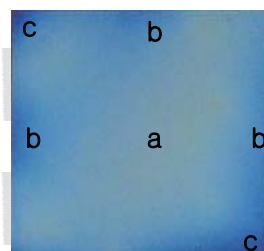
UV-NIL process using EPS

- 4 in. wafer with 9 successfully imprinted elements

- Residual layer thickness (RLT) distribution

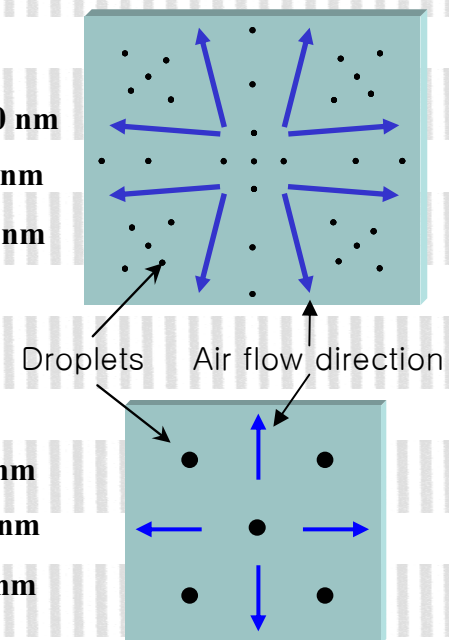


A: 90 - 100 nm
B: 60 - 70 nm
C: 50 - 60 nm



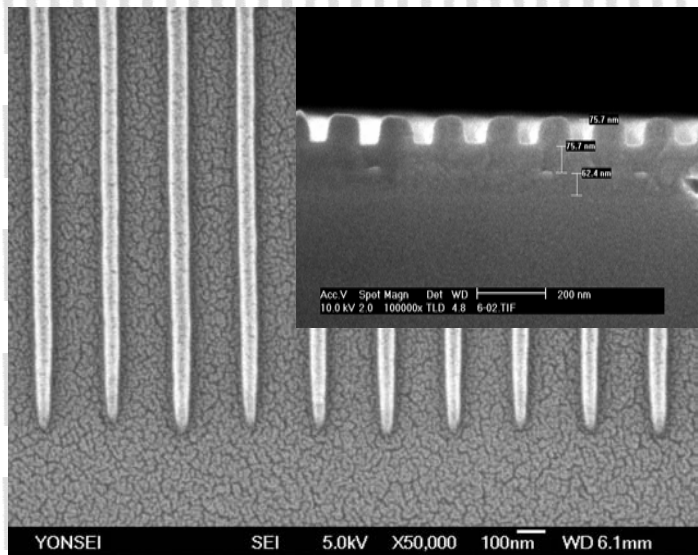
a: 70 - 80 nm
b: 50 - 60 nm
c: 40 - 50 nm

10 mm

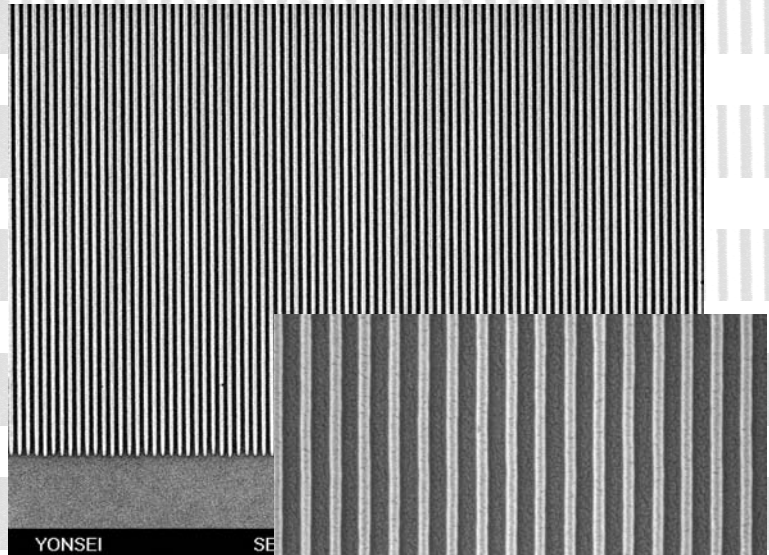


UV-NIL process using EPS

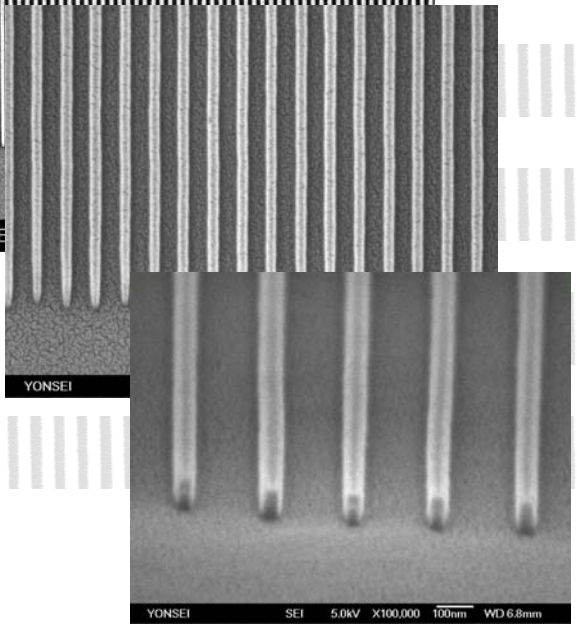
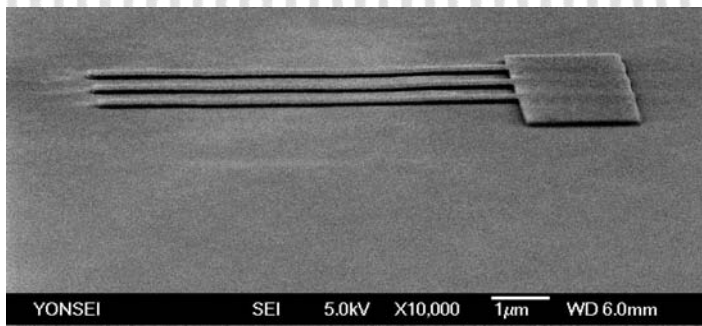
■ Imprint results



70 nm lines



50 nm lines



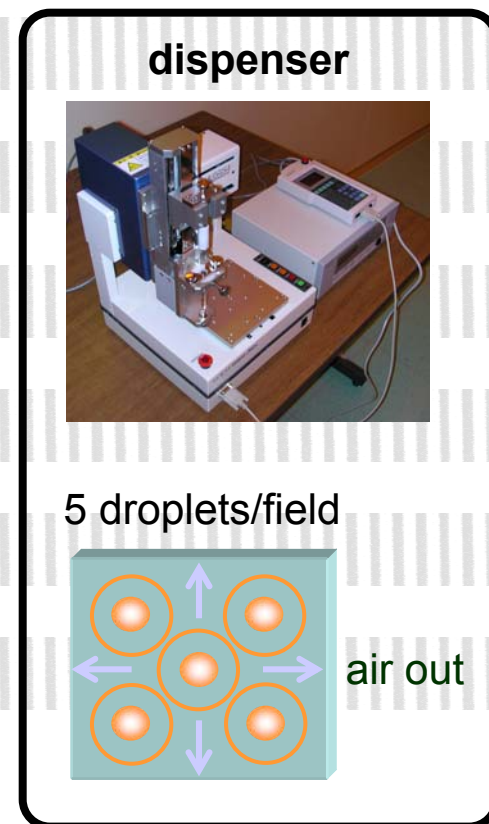
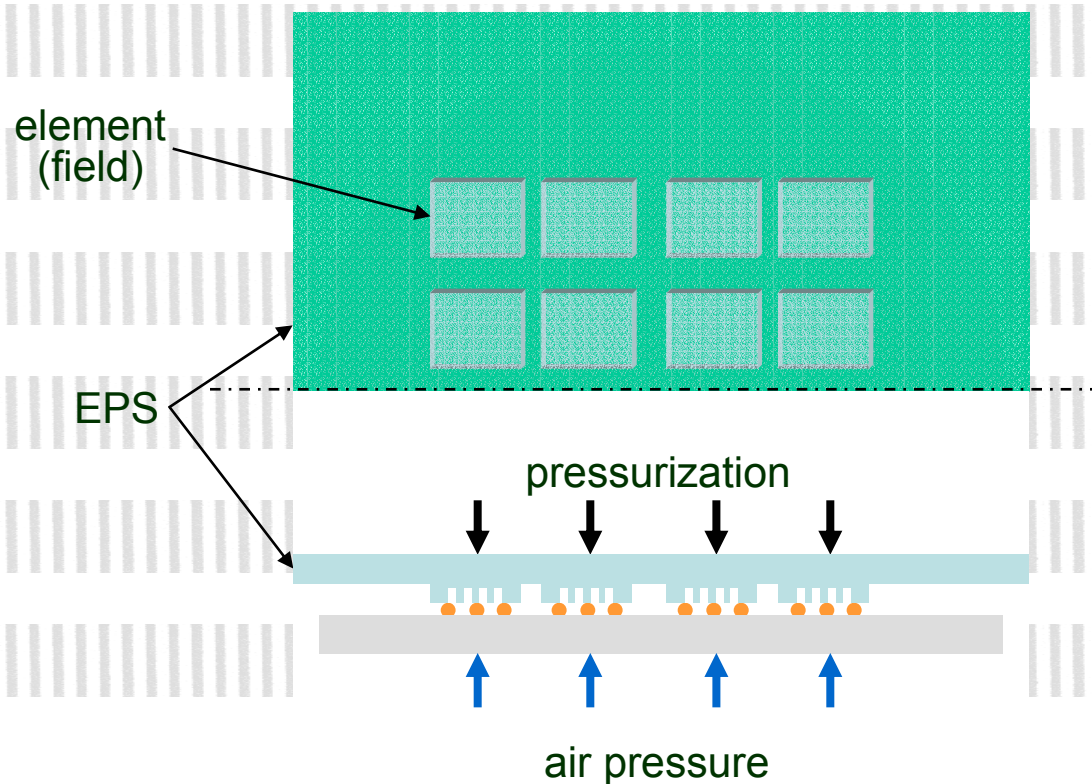
Process Technology

Single Step UV-NIL

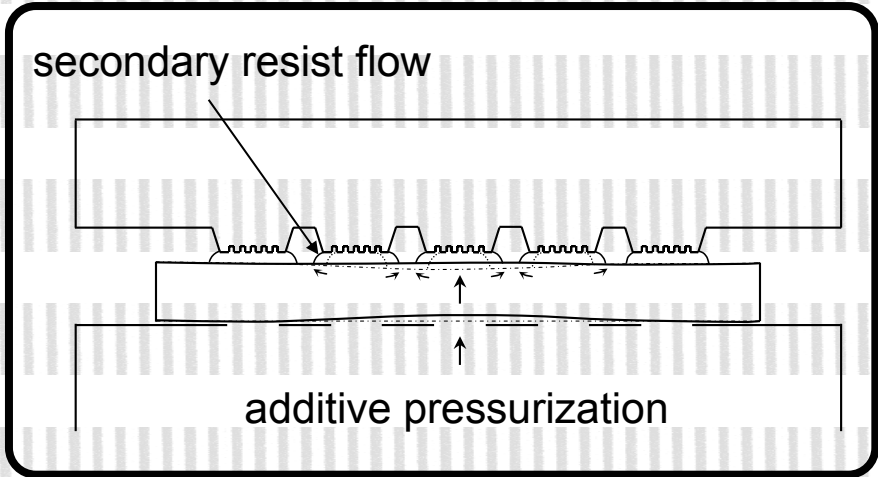
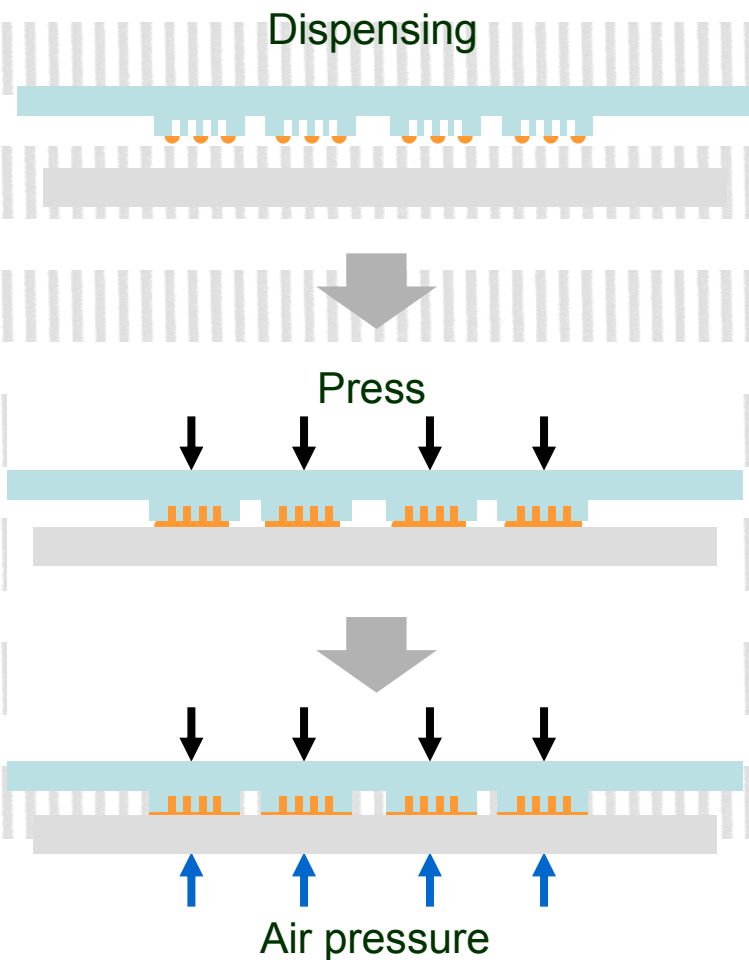
UV-NIL using EPS and Additive
Pressurization in an Atmospheric
Environment

Single-step UV-NIL in an atmospheric environment

- **Elementwise Patterned Stamp (EPS)**: avoid air entrapment
- **Additive Pressurization**: uniform residual layer thickness



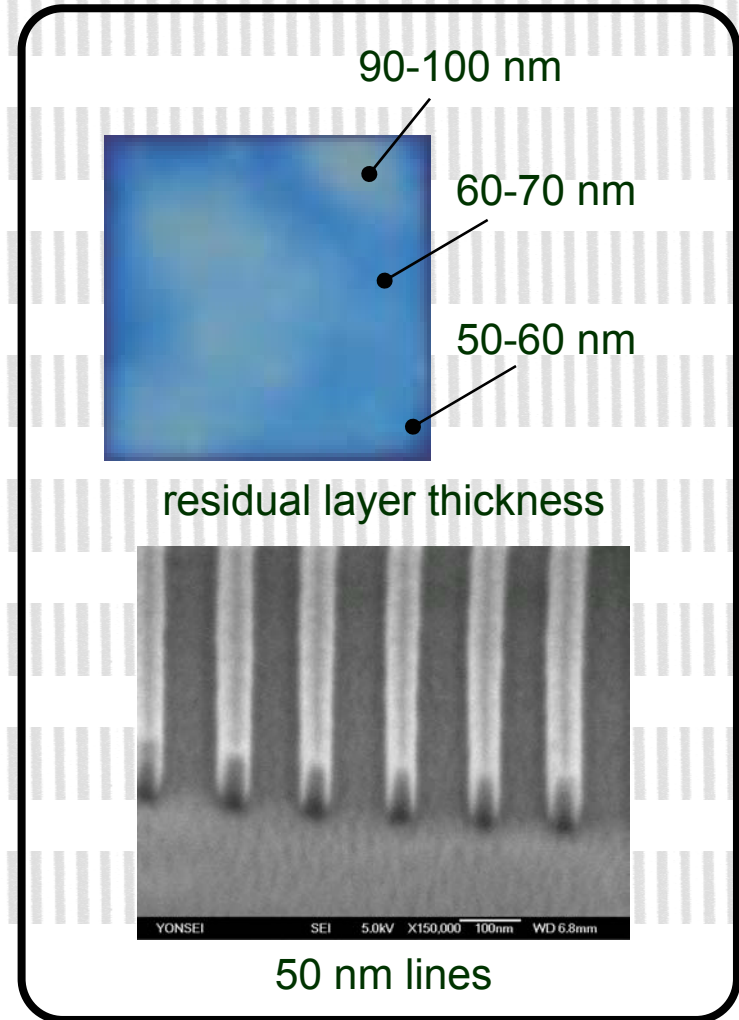
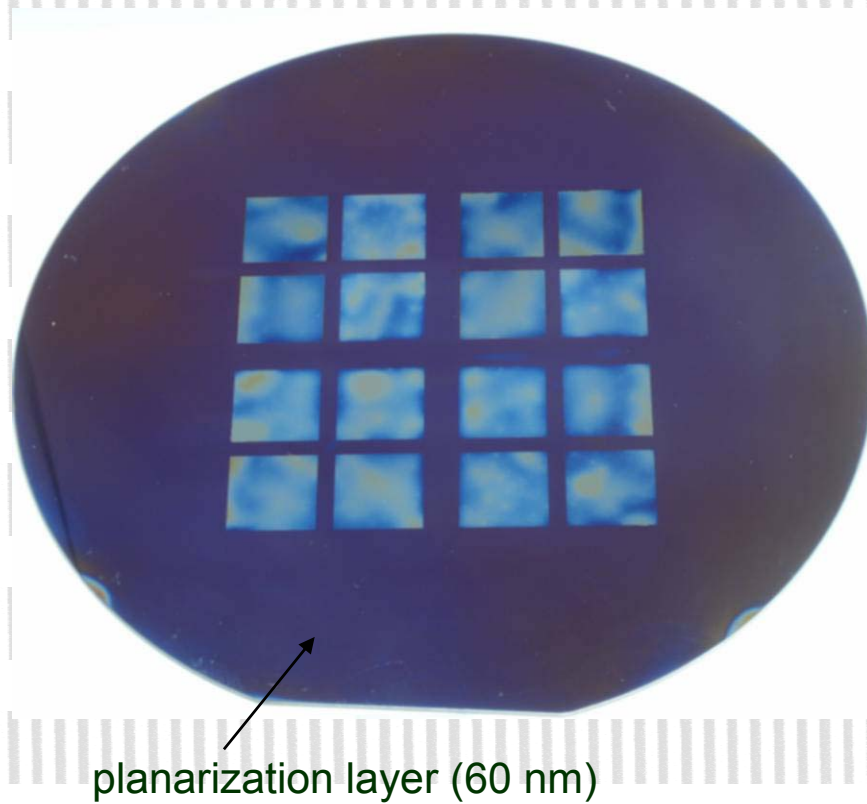
Single-step UV-NIL in an atmospheric environment



1st pressurization

2nd pressurization

Imprint results

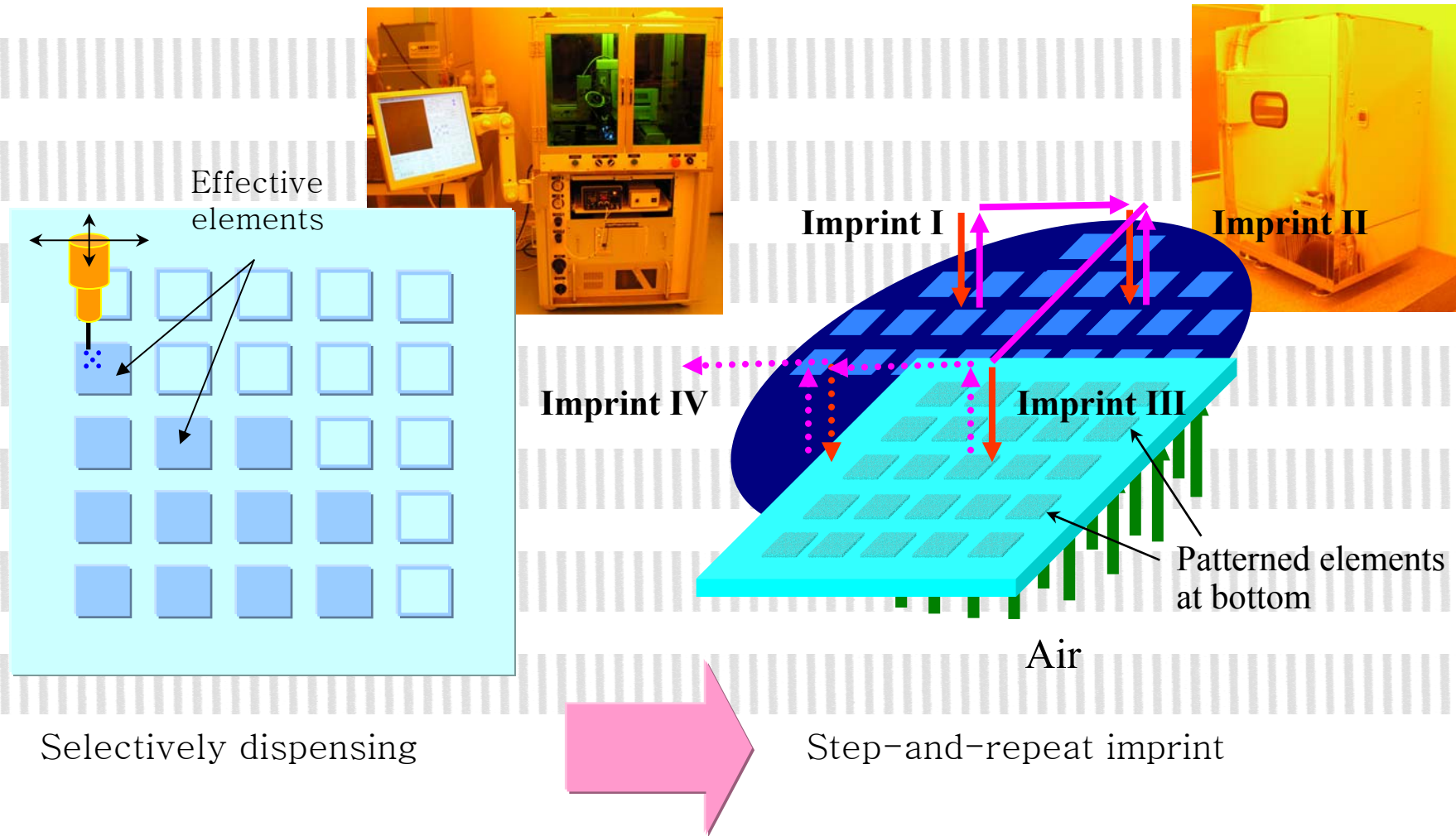


Process Technology

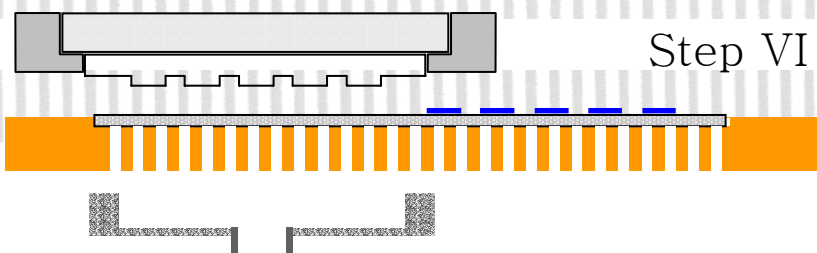
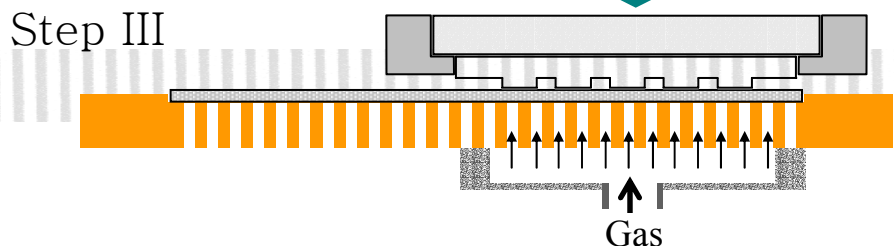
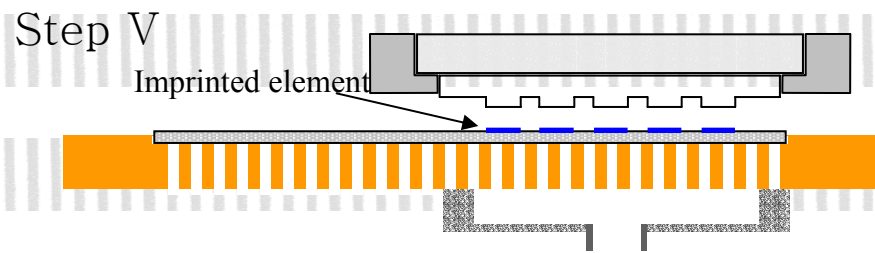
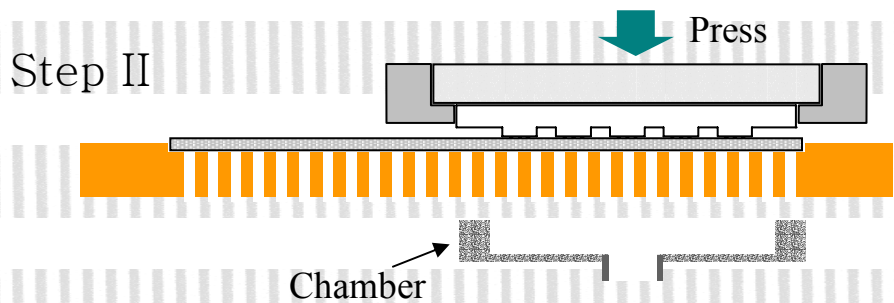
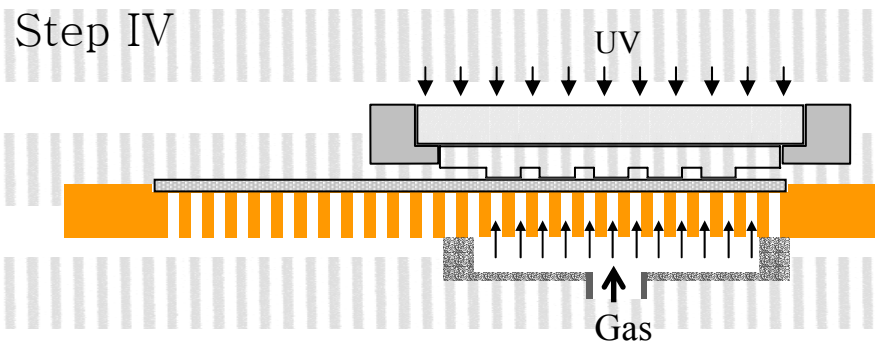
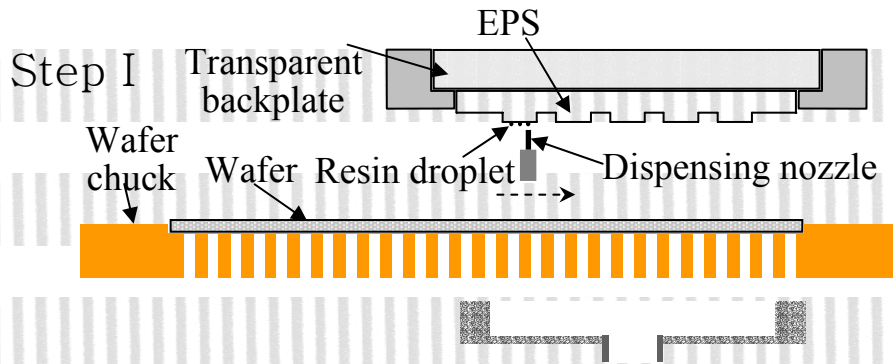
Step and Repeat UV-NIL

High Throughput Step-and-Repeat
UV-NIL using a Large Area EPS

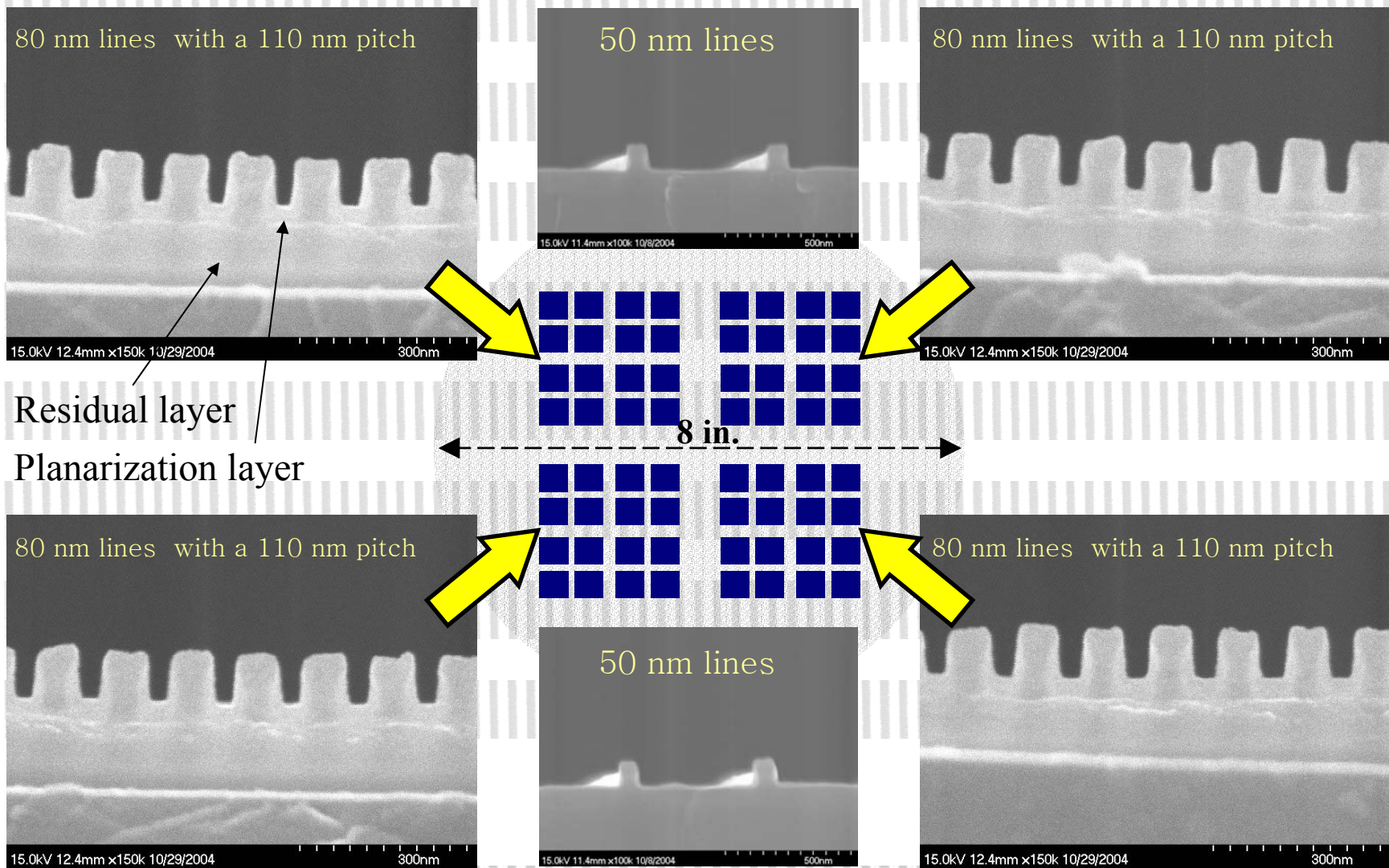
Step-and-repeat UV-NIL in an atmospheric environment



Step-and-repeat UV-NIL in an atmospheric environment



Step-and-repeat UV-NIL in an atmospheric environment



Application Technology

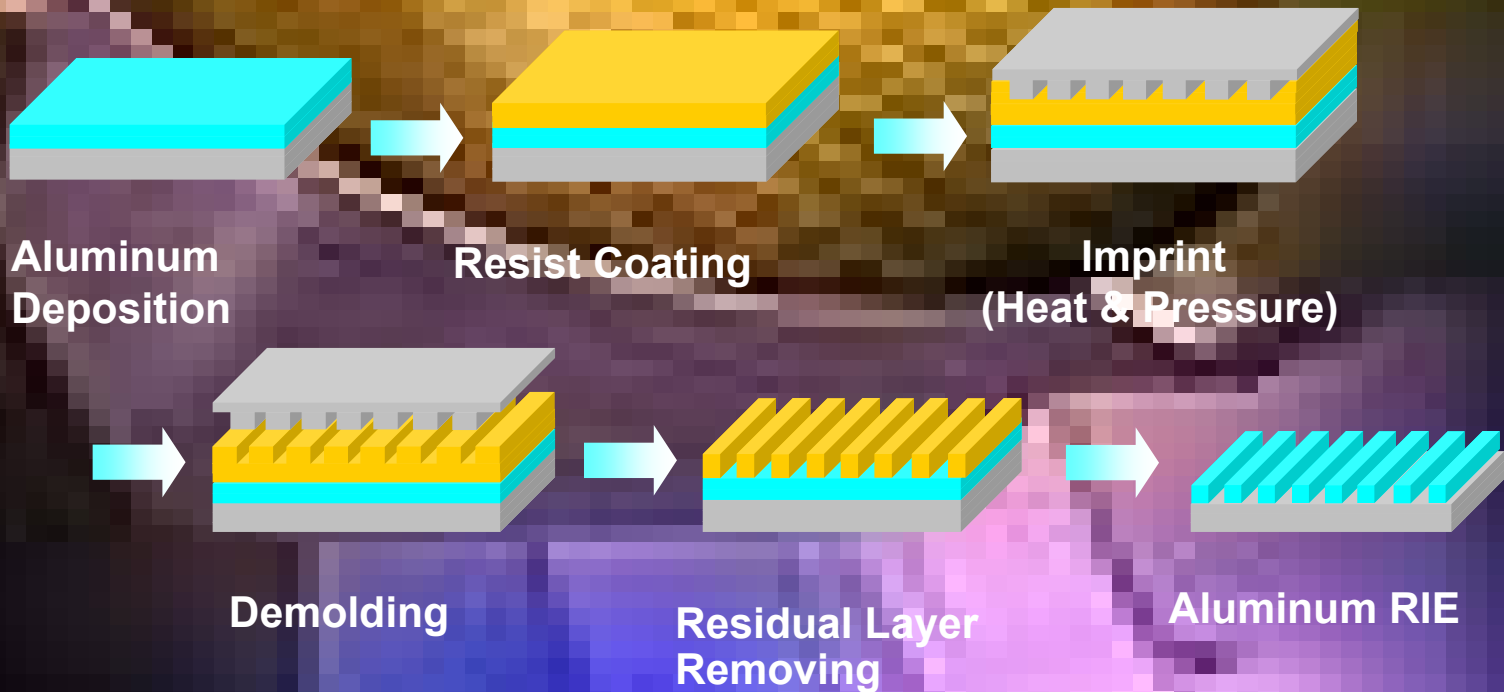
Nano Wire Grid Polarizer

Advantages of Nanoimprint Lithography

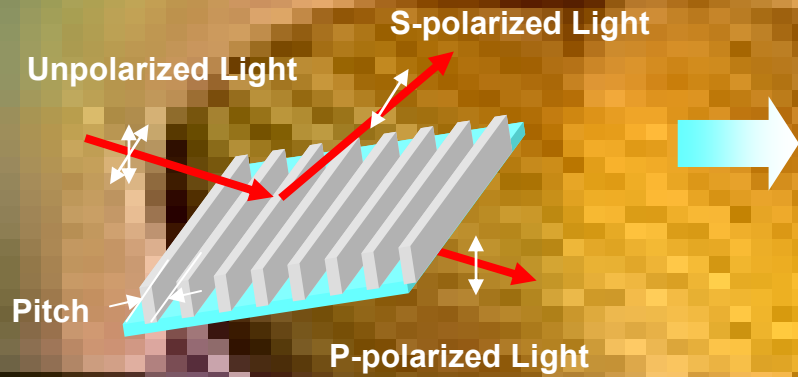
High resolution
Low tool cost

High throughput
Simple process

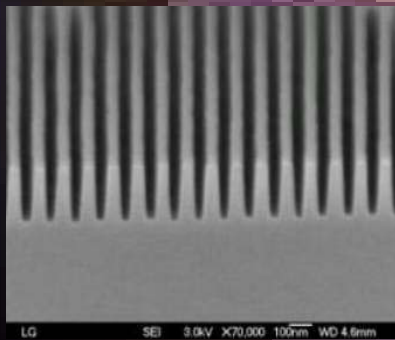
Process Flow (Nano Wire Grid Polarizer)



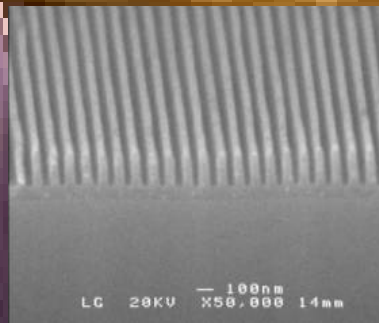
Development - Nano Wire Grid Polarizer



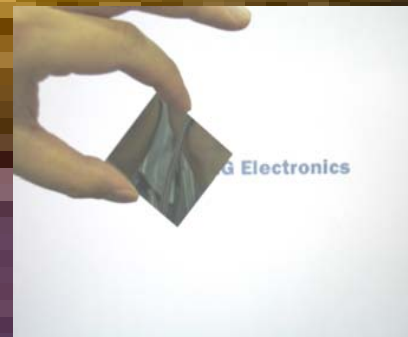
Projection TV



50 nm Half-Pitch Stamp



Imprinted Polymer Pattern

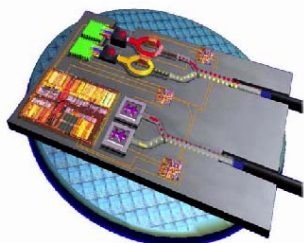


**Contrast Ratio > 2,000,
Transmission > 83 % at $\lambda = 470$ nm**

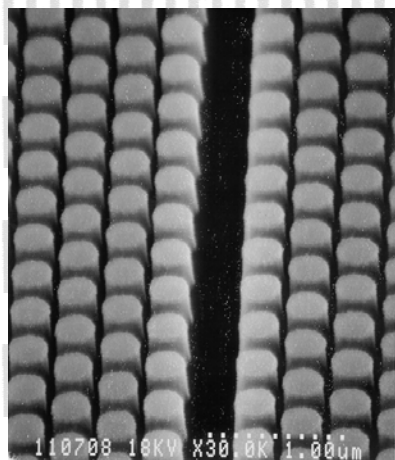
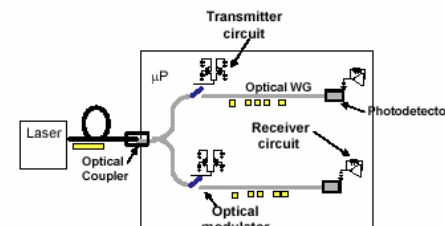
Application Technology

Photonic Band Gap Device

□ Nanoimprinting of Photonic Crystal Waveguides

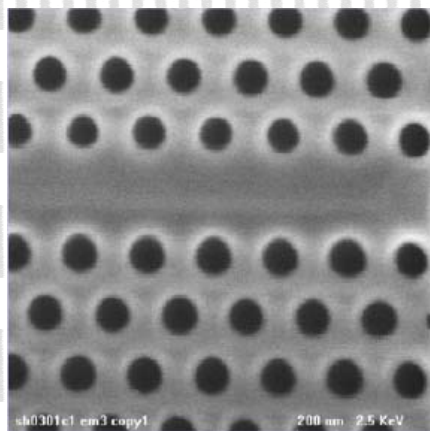


Future vision of hybrid optical integration of an optical transceiver with silicon photonic components and conventional CMOS drivers



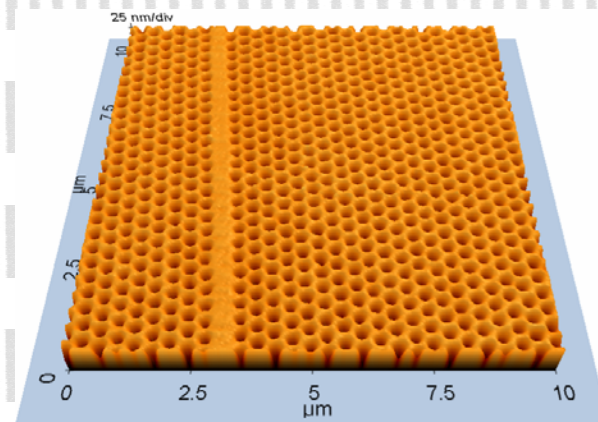
<SEM Image of Master>

Dimension
 $r = 150 \text{ nm}$
 $a = 400 \text{ nm}$

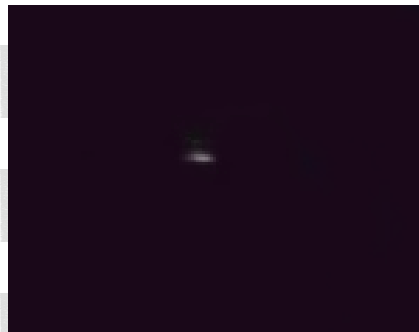
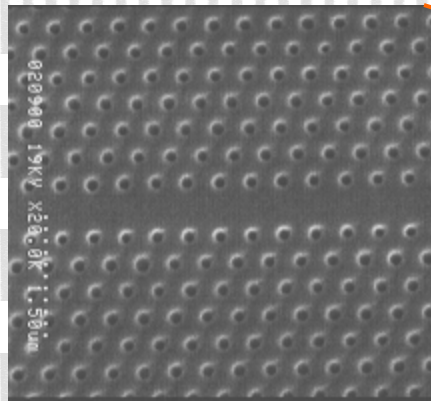


<SEM and AFM Images of Nanoimprinted Photonic Crystal Waveguide>

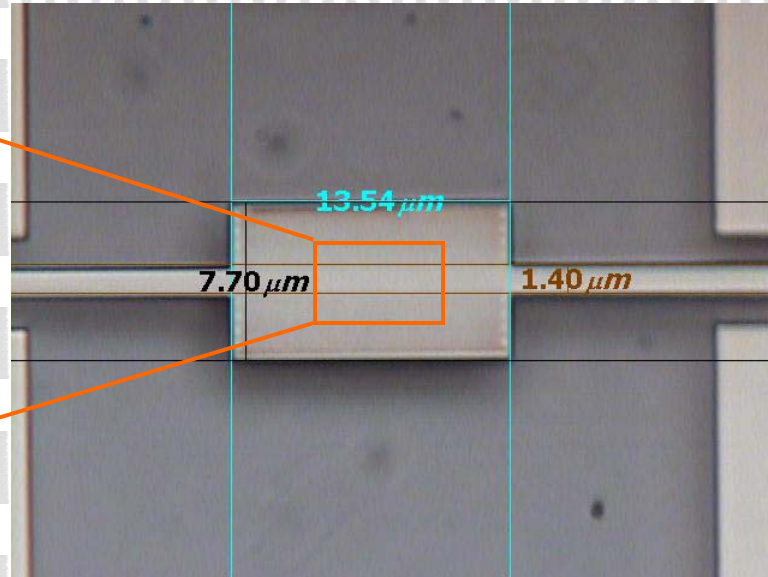
Dimension
 $r = 160 \text{ nm}$
 $a = 405 \text{ nm}$
 Height = 335~340 nm



❑ Completed Photonic Crystal Waveguide



<Near Field Pattern of Photonic Crystal Waveguide>



Dimension : 7.7 X 13.5 μm

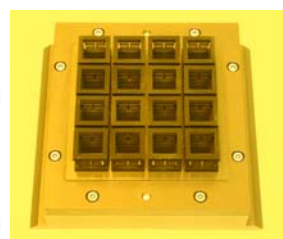
Tool Technology

Single-step UV-NIL tool

UV-based Nanopatterning Equipment - CNMM

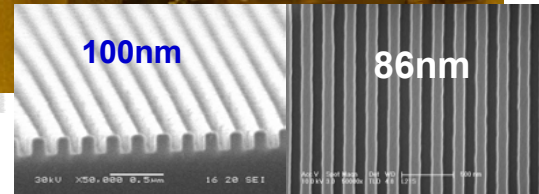
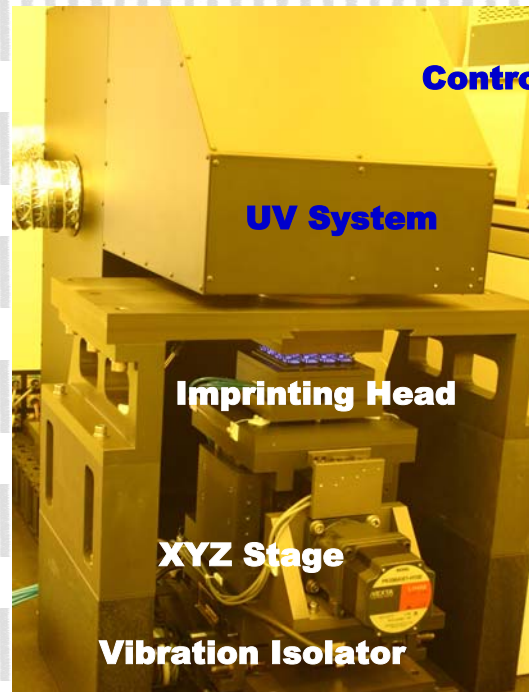
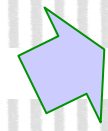
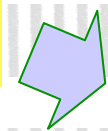
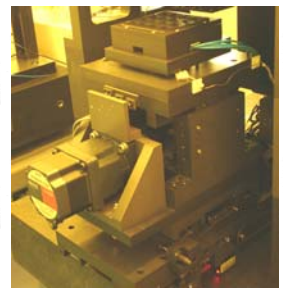
- Area : 4 inch Wafer
- Min. Feature Size ≤ 100 nm
- Chip-size Multi-Head Imprinting

- Nano-Precision Stage: 3nm
- 3-Axis Nano Leveling
- Overlay & Alignment
- UV Light Source
- Vibration Control



Flexure stage for parallelization

NanoImprint Equipment



Summary

- NIL has several advantages over optical lithography
 - High resolution (feature size ~ 10 nm)
 - low cost
- Challenging issues
 - Minimizing defects
 - Residual layer thickness control
 - 1×stamp inspection and cleaning
 - 10 nm scale overlay alignment

Thank You!